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DATE MAILED: 02/25/2005

APPLICATION NO.	FILING DATE	, FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
09/922,776	08/07/2001	Tetsuji Togawa	2001-1103	2271
7590 02/25/2005			EXAMINER	
WENDEROTH, LIND & PONACK, L.L.P.			ROSE, ROBERT A	
Suite 800 2033 "K" Street N.W.			ART UNIT	PAPER NUMBER
Washington, DC 20006			3723	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)				
	09/922,776	TOGAWA ET AL.				
Office Action Summary	Examiner	Art Unit				
	Robert Rose	3723				
The MAILING DATE of this communication ap	pears on the cover sheet with the	he correspondence address				
A SHORTENED STATUTORY PERIOD FOR REPL THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1. after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a rep. If NO period for reply is specified above, the maximum stopy period.  - Failure to reply within the set or extended period for reply will, by statut Any reply received by the Office later than three months after the mailir earned patent term adjustment. See 37 CFR 1.704(b).	136(a). In no event, however, may a reply to by within the statutory minimum of thirty (30 will apply and will expire SIX (6) MONTHS te, cause the application to become ABAND	be timely filed ) days will be considered timely. from the mailing date of this communication. ONED (35 U.S.C. § 133).				
Status	·					
1) Responsive to communication(s) filed on 08 /	November 2004.	•				
	s action is non-final.					
3) Since this application is in condition for allowa	, <del>-</del>					
closed in accordance with the practice under	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims	;					
4) ⊠ Claim(s) <u>1-14,16,17,19,20,43-46,50 and 51</u> is 4a) Of the above claim(s) is/are withdra 5) ⊠ Claim(s) <u>1-14,16,17,19,20 and 43-46</u> is/are al 6) ⊠ Claim(s) <u>50 and 51</u> is/are rejected.  7) □ Claim(s) is/are objected to.  8) □ Claim(s) are subject to restriction and/or	awn from consideration. llowed.					
Application Papers						
9) The specification is objected to by the Examin	er.					
10)☐ The drawing(s) filed on is/are: a)☐ accepted or b)☐ objected to by the Examiner.						
Applicant may not request that any objection to the	drawing(s) be held in abeyance.	See 37 CFR 1.85(a).				
Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the E		• , ,				
Priority under 35 U.S.C. § 119	/	100 / 101011 07 101111 1 0 102.				
<u> </u>						
a) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of:  1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority document application from the International Bureat* See the attached detailed Office action for a list	its have been received. Its have been received in Appli prity documents have been rec au (PCT Rule 17.2(a)).	cation No eived in this National Stage				
Attachment(s)						
1) Notice of References Cited (PTO-892)  4) Interview Summary (PTO-413)						
<ul> <li>2) Notice of Draftsperson's Patent Drawing Review (PTO-948)</li> <li>3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08 Paper No(s)/Mail Date</li> </ul>	Paper No(s)/Ma 5) Notice of Inform 6) Other:	nal Patent Application (PTO-152)				

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## **DETAILED ACTION**

- 1. Claims 15, 18, 21-42, and 47-49 have been canceled.
- 2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains.

    Patentability shall not be negatived by the manner in which the invention was made.
- Okumura et al in view of Oishi et al. Okumura et al disclose an apparatus for polishing a wafer comprising all of the subject matter set forth in applicant's claims above except for the limitation of the cleaning unit being capable of scrubbing both sides of the wafer. A wafer is picked up from a loading station(11) to a wafer loading position(13-1)(14-1) by a transfer system in the form of either a single dual-arm robot(10), or pair of robots(10A)(10B) as shown in fig. 11. The wafer is then picked up by a top ring of a polishing arm(13-2)(14-2) and applied to a polishing unit(13-4)(14-4). After polishing, the wafer is delivered to a cleaning device having a primary cleaning station(16-7) and secondary cleaning station(15-9), where the wafer is rinsed. The wafer is then delivered by the transfer system to a storage cassette. Alternatively, the rinsed wafer may be delivered to a second polishing unit. Note plural cleaning units shown in figures 2A and 5 with an associated turnover device for inverting the wafer. The cleaning unit(15) in figure 11 is deemed to meet the broad limitation of being disposed between

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the polishing unit(14) and the load/unload unit(11)(12), with the transfer device located in the space between the polishing unit and load/unload unit. Oishi et al discloses a wafer polishing and cleaning apparatus having a cleaning unit(12) which scrubs both sides of a wafer in the presence of a cleaning fluid. To provide brushes or other means for scrubbing both sides of the wafer in the apparatus of Okamura et al to insure that the maximum number of particles adhering to the wafer faces is removed would have been obvious in view of Oishi et al.

- 4. Claims 1-14, 16-17, 19-20, and 43-46 are allowed.
- 5. Applicant's arguments filed November 8, 2004 have been fully considered but they are not persuasive. With regard to rejected claims 50-51, while Okamura et al do not mention any means for scrubbing the wafer on both sides of the wafer in the cleaning unit, such structure is disclosed at least in Oishi et al for use after a polishing step, in order to remove the maximum number of particles from both surfaces. Oishi employs brushes to perform the scrubbing step in the presence of a cleaning liquid. To simply provide scrubbing brushes or other well known scrubbing means in the cleaning unit of Okamura et al for this reason is amply suggested by the art of record.

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within

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TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

6. Any inquiry concerning this communication should be directed to Robert Rose at telephone number (703) 308-1360.

rr

February 18, 2005.

ROBERT A. ROSE
PRIMARY EXAMINER
ART UNIT 323